IN THE CLAIMS

This is a complete and current listing of the claims, marked with status identifiers in parentheses. The following listing of claims will replace all prior versions and listings of claims in the application.

1. (Currently Amended) A component, comprising:

a glass substrate;

an organic light-emitting diode arranged on said glass substrate; ~~and~~

a glass cover, arranged over the organic light-emitting diode and glued at an edge to the glass substrate, said cover being produced from a glass plate by three-dimensional removal of material using a blasting method using commercial crystal corundum having an average particle size of 30 μm and a blasting pressure of 5 bar; and

wherein the edge of the glass cover has been superficially roughened.

2. (Cancelled)

3. (Previously Presented) The component of claim 1, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

4. (Previously Presented) The component of claim 3, wherein the adhesive is UV-curable.

5. (Previously Presented) The component of claim 3, wherein the adhesive is an epoxy resin.

6. (Currently Amended) A process for producing a component, comprising:

producing a plurality of recesses in a glass plate by three-dimensional removal of material using a blasting method using commercial crystal corundum having an average particle

size of 30 μm and a blasting pressure of 5 bar, said recesses having edges protected by a resist layer;

removing the protective resist layer of the edge; and

subjecting the edges of the recesses, lying bare, to a further blasting method using corundum having an average particle size of 9 μm and a blasting pressure of only 3 bar.

7. (Previously Presented) The process of claim 6, wherein an injector blasting nozzle is used as blasting nozzle in the initial blasting method.

8. (Previously Presented) The process of claim 6, wherein the distance between nozzle and workpiece in the initial blasting method is 80 mm.

9. (Currently Amended) The process of ~~claim6~~ claim 6, wherein edges having a roughness of about 30 rms are produced in the further blasting method in a blasting time of 30 seconds.

10. (Previously Presented) The process of claim 6, wherein after the recesses have been manufactured, the glass plate is used in order to encapsulate a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate, and wherein, following the encapsulation, the resultant components are at least partly individualized.

11. (Previously Presented) The process of claim 6, further comprising:

encapsulating a corresponding number of organic light-emitting diodes arranged correspondingly on a substrate using the glass plate, wherein the subsequently resulting components are at least partly individualized.

12. (Previously Presented) The component of claim 2, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

13. (Previously Presented) The component of claim 12, wherein the adhesive is

UV-curable.

14. (Previously Presented) The component of claim 4, wherein the adhesive is an epoxy resin.

15. (Previously Presented) The component of claim 12, wherein the adhesive is an epoxy resin.

16. (Previously Presented) The component of claim 13, wherein the adhesive is an epoxy resin.

17. (Previously Presented) The process of claim 6, wherein the component includes a glass substrate, an organic light-emitting diode arranged on said glass substrate, and a glass cover, arranged over the organic light-emitting diode and glued at an edge to the glass substrate, said cover being produced from a glass plate by the three-dimensional removal of material using the blasting method.

18. (Previously Presented) The process of claim 6, wherein the glass cover is bonded to the glass substrate using an organic adhesive.

19. (Previously Presented) The process of claim 18, wherein the adhesive is UV-curable.

20. (Previously Presented) The process of claim 18, wherein the adhesive is an epoxy resin.

21. (Previously Presented) The process of claim 19, wherein the adhesive is an epoxy resin.

22. (Previously Presented) The process of claim 17, wherein the adhesive is an epoxy resin.